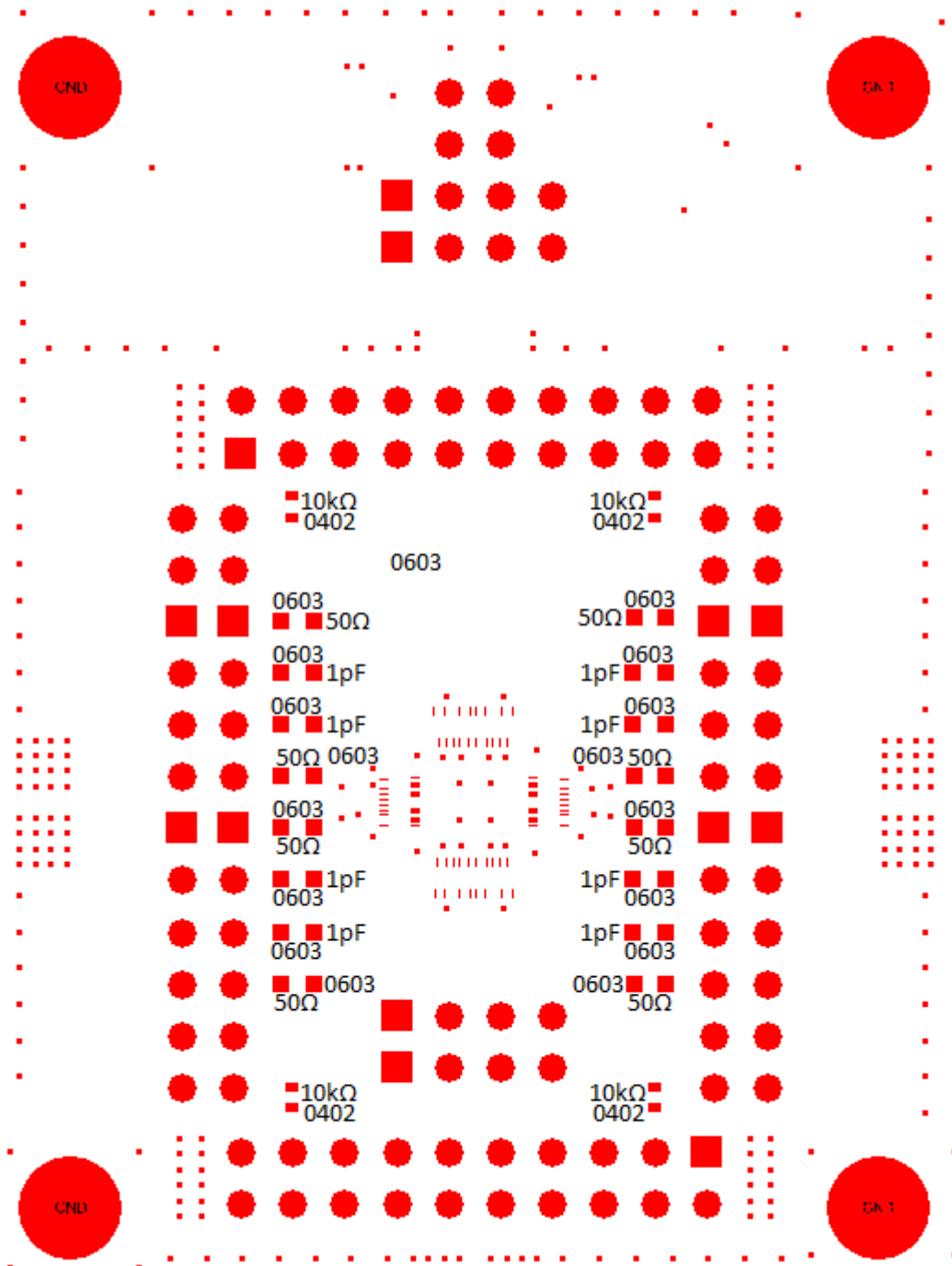


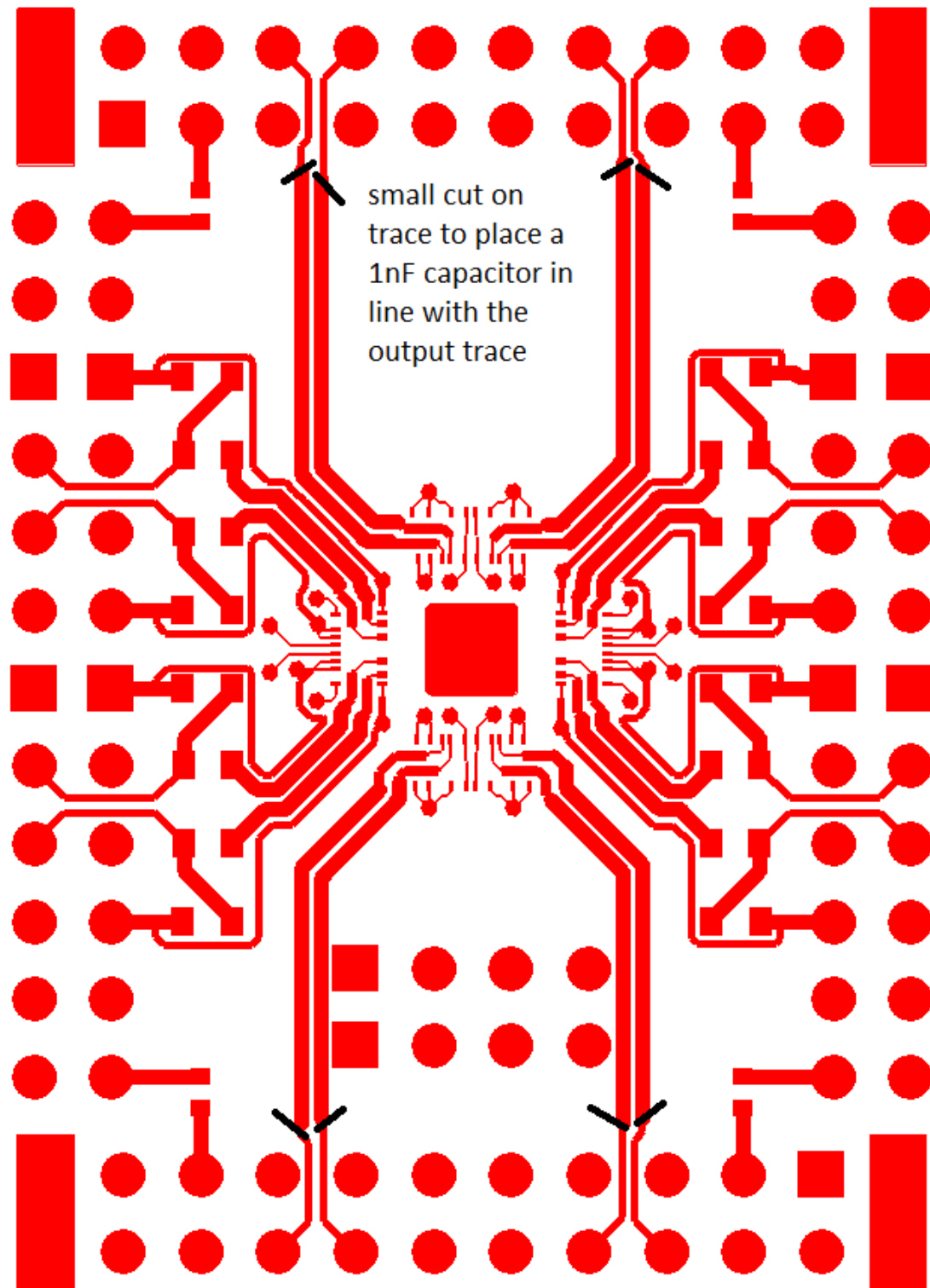
FastAmp ASIC Testboard
Feb 13 2018

DEVICE_TYPE	VALUE	QUANTITY	PART NUMBER
CSMD0402-0.1UF,10%,0402,25V	0.1UF	2	
CSMD0402-10UF,10%,0402,25V	10UF	2	
CSMD0603-1PF,10%,0603,25V	1PF	8	
CSMD0402-1NF,10%,0402,25V	1NF	16	
FASTAMP_CHIP	ASIC	1	
LT1761-SD		2	LT1761IS5-SD#TRMPBF / LT1761ES5-SD#TRMPBF
RSMD0402-270,1%,0402	270	1	
RSMD0402-30,1%,0402	30	1	
RSMD0402-10K,1%,0402	10K	4	
RSMD0402-390,1%,0402	390	1	
RSMD0402-200,1%,0402	200	1	
RSMD0402-100,1%,0402	100	2	
RSMD0402-333,1%,0402	333	1	
RSMD0402-470,1%,0402	470	1	
RSMD0603-50,1%,0603	50	8	

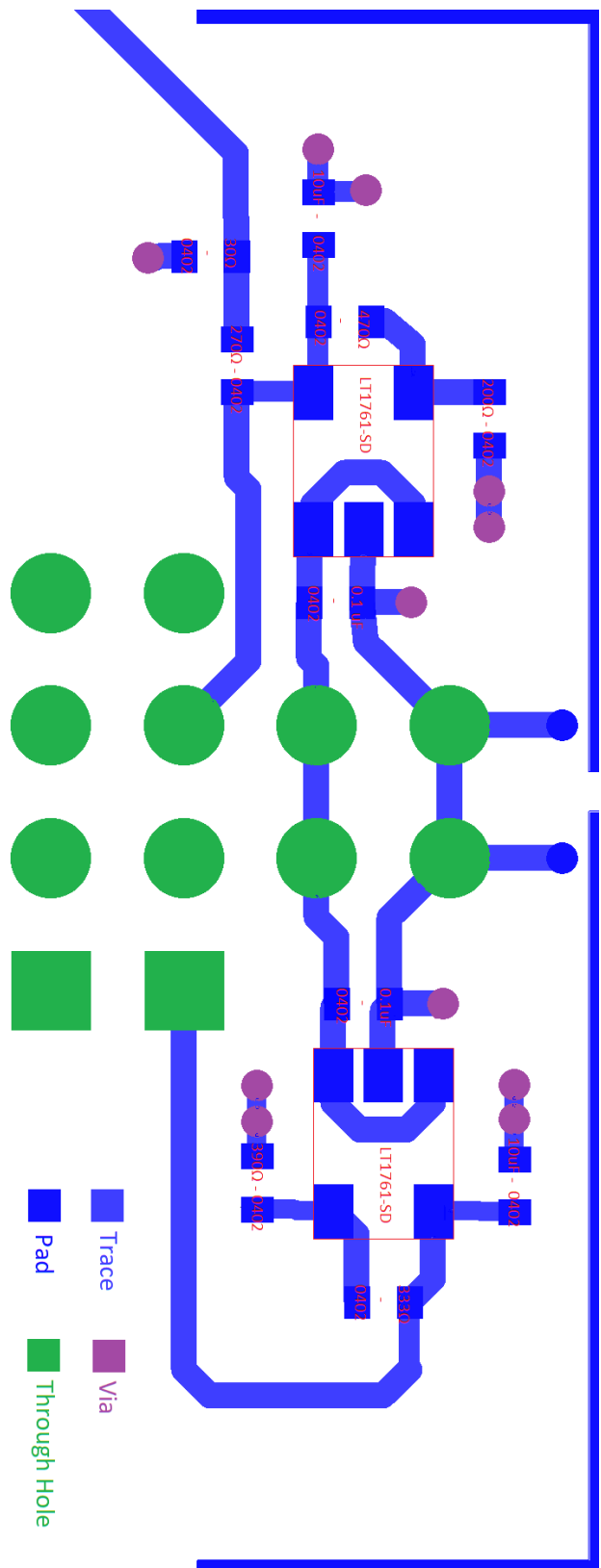
The following is the stuffing diagram used for the top portion of the board. The tiny dots are vias, while the big squares and circles are through holes.



This image shows the modifications that were made on the board to capacitive couple the output signals of the channels. Each black line represents where the trace was cut to create small pads where a 0402 1nF capacitor can be soldered.



The following image shows how to stuff the parts on the board's back side, and the orientation reflects what one sees at the portion of the board where the supply power goes in.



The following image shows how to stuff the parts on the board's back side, behind where the ASIC is bonded.

